Material Composition Data

Product: HC49

Timing Is Everything

HC49 - Standard Crystal

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base Header					
	Steel	Fe		358.748	96.44
		C		0.179	0.05
		Si	7440-21-3	0.037	0.01
		Mn	7439-96-5	0.611	0.16
	Chemical Plating	Ni	7440-02-0	3.814	1.03
		P	7723-14-0	0.371	0.10
	Electro Plating	Ni	7440-02-0	8.240	2.22
Base clip					
	Copper Alloy	Cu	7440-50-8	7.014	53.95
		Ni	7440-02-0	2.149	16.53
		Fe	7439-89-6	0.035	0.27
		Mn	7439-96-5	0.071	0.55
		Zn	7440-66-6	3.731	28.70
Base Glass					
	Hard Glass	Tridymite	7440-28-0	11.900	82.01
		Aluminium Oxide	1344-28-1	1.570	10.82
		Disodium-oxide	7440-50-8	0.800	5.51
		Dipotassium-oxide	7440-50-8	0.240	1.65
Base terminal wire					
	High alloyed Steel	Co	7440-48-4	6.868	16.51
		Fe	7439-89-6	21.291	51.18
		Ni	7440-02-0	11.687	28.09
		Mn	7439-96-5	0.100	0.24
		Si	7440-21-3	0.048	0.12
		C	7440-44-0	0.004	0.01
	Chemical Plating	Ni	7440-02-0	0.434	1.04
		P	7723-14-0	0.042	0.10
	Solder	Sn	7440.31-5	1.086	2.61
		Ag	7440-22-4	0.034	0.08
		Cu	7440-50-8	0.006	0.01
Cover					
	Copper Alloy	Cu	7440-50-8	231.300	62.62
		Ni	7440-02-0	60.876	16.48
		Zn	7440-66-6	66.780	18.08
		Mn	7439-96-5	0.760	0.21
		Fe	7439-89-6	0.284	0.08
	Electro Plating	Ni	7440-02-0	9.400	2.54
Crystal blank					
	Quartz	SiO2	14808-60-7	27.567	94.84
	Silver plating	Ag	7440-22-4	1.500	5.16
Bonding Adhesive					
	Silver epoxy	Ag	7440-22-4	2.800	70.00
		Epoxy resin		1.200	30.00

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
			Total Mass:	843.577 mg	

John Hems

John Hems
Quality Manager
Email: j.hems@golledge.com